

# China Fan-in Wafer Level Packaging Market Research Report 2017

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## Abstracts

### Notes:

Sales, means the sales volume of Fan-in Wafer Level Packaging

Revenue, means the sales value of Fan-in Wafer Level Packaging

This report studies Fan-in Wafer Level Packaging in China market, focuses on the top players in China market, with capacity, production, price, revenue and market share for each manufacturer, covering

STATS ChipPAC

STMicroelectronics

TSMC

Texas Instruments

Rudolph Technologies

SEMES

SUSS MicroTec

Ultratech

## FlipChip International

IWLPC

Market Segment by Regions (provinces), covering

South China

East China

Southwest China

Northeast China

North China

Central China

Northwest China

Split by product Type, with production, revenue, price, market share and growth rate of each type, can be divided into

Type I

Type II

Type III

Split by Application, this report focuses on consumption, market share and growth rate of Fan-in Wafer Level Packaging in each application, can be divided into

CMOS image sensor

Wireless connectivity

Logic and memory IC

MEMS and sensor

Analog and mixed IC

## Contents

### China Fan-in Wafer Level Packaging Market Research Report 2017

#### **1 FAN-IN WAFER LEVEL PACKAGING MARKET OVERVIEW**

- 1.1 Product Overview and Scope of Fan-in Wafer Level Packaging
- 1.2 Fan-in Wafer Level Packaging Segment by Type
  - 1.2.1 China Production Market Share of Fan-in Wafer Level Packaging Type in 2015
  - 1.2.2 Type I
  - 1.2.3 Type II
  - 1.2.4 Type III
- 1.3 Applications of Fan-in Wafer Level Packaging
  - 1.3.1 Fan-in Wafer Level Packaging Consumption Market Share by Application in 2015
  - 1.3.2 CMOS image sensor
  - 1.3.3 Wireless connectivity
  - 1.3.4 Logic and memory IC
  - 1.3.5 MEMS and sensor
  - 1.3.6 Analog and mixed IC
- 1.4 China Market Size (Value) of Fan-in Wafer Level Packaging (2011-2021)
- 1.5 China Fan-in Wafer Level Packaging Status and Outlook
- 1.6 Government Policies

#### **2 CHINA FAN-IN WAFER LEVEL PACKAGING MARKET COMPETITION BY MANUFACTURERS**

- 2.1 China Fan-in Wafer Level Packaging Capacity, Production and Share by Manufacturers (2015 and 2016)
- 2.2 China Fan-in Wafer Level Packaging Revenue and Share by Manufacturers (2015 and 2016)
- 2.3 China Fan-in Wafer Level Packaging Average Price by Manufacturers (2015 and 2016)
- 2.4 Manufacturers Fan-in Wafer Level Packaging Manufacturing Base Distribution, Sales Area, Product Type
- 2.5 Fan-in Wafer Level Packaging Market Competitive Situation and Trends
  - 2.5.1 Fan-in Wafer Level Packaging Market Concentration Rate
  - 2.5.2 Fan-in Wafer Level Packaging Market Share of Top 3 and Top 5 Manufacturers

#### **3 CHINA FAN-IN WAFER LEVEL PACKAGING MANUFACTURERS**

## **PROFILES/ANALYSIS**

### **3.1 STATS ChipPAC**

3.1.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors

3.1.2 Fan-in Wafer Level Packaging Product Type, Application and Specification

3.1.2.1 Type I

3.1.2.2 Type II

3.1.3 STATS ChipPAC Fan-in Wafer Level Packaging Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)

3.1.4 Main Business/Business Overview

### **3.2 STMicroelectronics**

3.2.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors

3.2.2 Fan-in Wafer Level Packaging Product Type, Application and Specification

3.2.2.1 Type I

3.2.2.2 Type II

3.2.3 STMicroelectronics 95 Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)

3.2.4 Main Business/Business Overview

### **3.3 TSMC**

3.3.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors

3.3.2 Fan-in Wafer Level Packaging Product Type, Application and Specification

3.3.2.1 Type I

3.3.2.2 Type II

3.3.3 TSMC 110 Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)

3.3.4 Main Business/Business Overview

### **3.4 Texas Instruments**

3.4.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors

3.4.2 Fan-in Wafer Level Packaging Product Type, Application and Specification

3.4.2.1 Type I

3.4.2.2 Type II

3.4.3 Texas Instruments Jan Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)

3.4.4 Main Business/Business Overview

### **3.5 Rudolph Technologies**

- 3.5.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors
- 3.5.2 Fan-in Wafer Level Packaging Product Type, Application and Specification
  - 3.5.2.1 Type I
  - 3.5.2.2 Type II
- 3.5.3 Rudolph Technologies Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)
- 3.5.4 Main Business/Business Overview
- 3.6 SEMES
  - 3.6.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors
  - 3.6.2 Fan-in Wafer Level Packaging Product Type, Application and Specification
    - 3.6.2.1 Type I
    - 3.6.2.2 Type II
  - 3.6.3 SEMES Million USD Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)
  - 3.6.4 Main Business/Business Overview
- 3.7 SUSS MicroTec
  - 3.7.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors
  - 3.7.2 Fan-in Wafer Level Packaging Product Type, Application and Specification
    - 3.7.2.1 Type I
    - 3.7.2.2 Type II
  - 3.7.3 SUSS MicroTec Chemical & Material Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)
  - 3.7.4 Main Business/Business Overview
- 3.8 Ultratech
  - 3.8.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors
  - 3.8.2 Fan-in Wafer Level Packaging Product Type, Application and Specification
    - 3.8.2.1 Type I
    - 3.8.2.2 Type II
  - 3.8.3 Ultratech Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)
  - 3.8.4 Main Business/Business Overview
- 3.9 FlipChip International
  - 3.9.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors
  - 3.9.2 Fan-in Wafer Level Packaging Product Type, Application and Specification

3.9.2.1 Type I

3.9.2.2 Type II

3.9.3 FlipChip International Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)

3.9.4 Main Business/Business Overview

3.10 IWLPC

3.10.1 Company Basic Information, Manufacturing Base, Sales Area and Its Competitors

3.10.2 Fan-in Wafer Level Packaging Product Type, Application and Specification

3.10.2.1 Type I

3.10.2.2 Type II

3.10.3 IWLPC Capacity, Production, Revenue, Price and Gross Margin (2015 and 2016)

3.10.4 Main Business/Business Overview

#### **4 CHINA FAN-IN WAFER LEVEL PACKAGING CAPACITY, PRODUCTION, REVENUE, CONSUMPTION, EXPORT AND IMPORT (2011-2016)**

4.1 China Fan-in Wafer Level Packaging Capacity, Production and Growth (2011-2016)

4.2 China Fan-in Wafer Level Packaging Revenue and Growth (2011-2016)

4.3 China Fan-in Wafer Level Packaging Production, Consumption, Export and Import (2011-2016)

#### **5 CHINA FAN-IN WAFER LEVEL PACKAGING PRODUCTION, REVENUE (VALUE), PRICE TREND BY TYPE**

5.1 China Fan-in Wafer Level Packaging Production and Market Share by Type (2011-2016)

5.2 China Fan-in Wafer Level Packaging Revenue and Market Share by Type (2011-2016)

5.3 China Fan-in Wafer Level Packaging Price by Type (2011-2016)

5.4 China Fan-in Wafer Level Packaging Production Growth by Type (2011-2016)

#### **6 CHINA FAN-IN WAFER LEVEL PACKAGING MARKET ANALYSIS BY APPLICATION**

6.1 China Fan-in Wafer Level Packaging Consumption and Market Share by Application (2011-2016)

6.2 China Fan-in Wafer Level Packaging Consumption Growth Rate by Application

(2011-2016)

### 6.3 Market Drivers and Opportunities

6.3.1 Potential Application

6.3.2 Emerging Markets/Countries

## **7 CHINAFAN-IN WAFER LEVEL PACKAGING MARKET ANALYSIS BY REGIONS (PROVINCES)**

7.1 China Fan-in Wafer Level Packaging Production, Production Value and Price by Regions (Provinces)(2011-2016)

7.1.1 China Fan-in Wafer Level Packaging Production and Market Share by Regions (Provinces)(2011-2016)

7.1.2 China Fan-in Wafer Level Packaging Production Value and Market Share by Regions (Provinces)(2011-2016)

7.1.3 China Fan-in Wafer Level Packaging Sales Price by Regions (Provinces)(2011-2016)

7.2 China Fan-in Wafer Level Packaging Consumption by Regions (Provinces)(2011-2016)

7.3 China Fan-in Wafer Level Packaging Production, Consumption, Export and Import (2011-2016)

## **8 FAN-IN WAFER LEVEL PACKAGING MANUFACTURING COST ANALYSIS**

8.1 Fan-in Wafer Level Packaging Key Raw Materials Analysis

8.1.1 Key Raw Materials

8.1.2 Price Trend of Key Raw Materials

8.1.3 Key Suppliers of Raw Materials

8.1.4 Market Concentration Rate of Raw Materials

8.2 Proportion of Manufacturing Cost Structure

8.2.1 Raw Materials

8.2.2 Labor Cost

8.2.3 Manufacturing Expenses

8.3 Manufacturing Process Analysis of Fan-in Wafer Level Packaging

## **9 INDUSTRIAL CHAIN, SOURCING STRATEGY AND DOWNSTREAM BUYERS**

9.1 Fan-in Wafer Level Packaging Industrial Chain Analysis

9.2 Upstream Raw Materials Sourcing

9.3 Raw Materials Sources of Fan-in Wafer Level Packaging Major Manufacturers in



2015

9.4 Downstream Buyers

## **10 MARKETING STRATEGY ANALYSIS, DISTRIBUTORS/TRADERS**

10.1 Marketing Channel

10.1.1 Direct Marketing

10.1.2 Indirect Marketing

10.1.3 Marketing Channel Development Trend

10.2 Market Positioning

10.2.1 Pricing Strategy

10.2.2 Brand Strategy

10.2.3 Target Client

10.3 Distributors/Traders List

## **11 MARKET EFFECT FACTORS ANALYSIS**

11.1 Technology Progress/Risk

11.1.1 Substitutes Threat

11.1.2 Technology Progress in Related Industry

11.2 Consumer Needs/Customer Preference Change

11.3 Economic/Political Environmental Change

## **12 CHINA FAN-IN WAFER LEVEL PACKAGING MARKET FORECAST (2016-2021)**

12.1 China Fan-in Wafer Level Packaging Capacity, Production, Revenue Forecast (2016-2021)

12.2 China Fan-in Wafer Level Packaging Production, Import, Export and Consumption Forecast (2016-2021)

12.3 China Fan-in Wafer Level Packaging Production Forecast by Type (2016-2021)

12.4 China Fan-in Wafer Level Packaging Consumption Forecast by Application (2016-2021)

12.5 China Fan-in Wafer Level Packaging Production, Consumption, Import and Export Forecast by Regions (Provinces)(2016-2021)

12.5.1 China Fan-in Wafer Level Packaging Production Forecast by Regions (Provinces)(2016-2021)

12.5.2 China Fan-in Wafer Level Packaging Consumption Forecast by Regions (Provinces)(2016-2021)

12.5.3 China Fan-in Wafer Level Packaging Production, Consumption, Import and

Export Forecast by Regions (Provinces)(2016-2021)  
12.6 Fan-in Wafer Level Packaging Price Forecast (2016-2021)

## **13 RESEARCH FINDINGS AND CONCLUSION**

## **14 APPENDIX**

Methodology

Analyst Introduction

Data Source

The report requires updating with new data and is sent in 2-3 business days after order is placed.

## List Of Tables

### LIST OF TABLES AND FIGURES

Figure Picture of Fan-in Wafer Level Packaging

Figure China Production Market Share of Fan-in Wafer Level Packaging by Type in 2015

Figure Product Picture of Type I

Table Major Manufacturers of Type I

Figure Product Picture of Type II

Table Major Manufacturers of Type II

Figure Product Picture of Type III

Table Major Manufacturers of Type III

Table Fan-in Wafer Level Packaging Consumption Market Share by Application in 2015

Figure CMOS image sensor Examples

Figure Wireless connectivity Examples

Figure Logic and memory IC Examples

Figure MEMS and sensor Examples

Figure Analog and mixed IC Examples

Figure China Fan-in Wafer Level Packaging Revenue (Million USD) and Growth Rate (2011-2021)

Table China Fan-in Wafer Level Packaging Capacity of Key Manufacturers (2015 and 2016)

Table China Fan-in Wafer Level Packaging Capacity Market Share of Key Manufacturers (2015 and 2016)

Figure China Fan-in Wafer Level Packaging Capacity of Key Manufacturers in 2015

Figure China Fan-in Wafer Level Packaging Capacity of Key Manufacturers in 2016

Table China Fan-in Wafer Level Packaging Production of Key Manufacturers (2015 and 2016)

Table China Fan-in Wafer Level Packaging Production Share by Manufacturers (2015 and 2016)

Figure 2015 Fan-in Wafer Level Packaging Production Share by Manufacturers

Figure 2016 Fan-in Wafer Level Packaging Production Share by Manufacturers

Table China Fan-in Wafer Level Packaging Revenue (Million USD) by Manufacturers (2015 and 2016)

Table China Fan-in Wafer Level Packaging Revenue Share by Manufacturers (2015 and 2016)

Table 2015 China Fan-in Wafer Level Packaging Revenue Share by Manufacturers

Table 2016 China Fan-in Wafer Level Packaging Revenue Share by Manufacturers

Table China Market Fan-in Wafer Level Packaging Average Price of Key Manufacturers (2015 and 2016)

Figure China Market Fan-in Wafer Level Packaging Average Price of Key Manufacturers in 2015

Table Manufacturers Fan-in Wafer Level Packaging Manufacturing Base Distribution and Sales Area

Table Manufacturers Fan-in Wafer Level Packaging Product Type

Figure Fan-in Wafer Level Packaging Market Share of Top 3 Manufacturers

Figure Fan-in Wafer Level Packaging Market Share of Top 5 Manufacturers

Table STATS ChipPAC Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table STATS ChipPAC Fan-in Wafer Level Packaging Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure STATS ChipPAC Fan-in Wafer Level Packaging Market Share (2011-2016)

Table STMicroelectronics Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table STMicroelectronics Fan-in Wafer Level Packaging Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure STMicroelectronics Fan-in Wafer Level Packaging Market Share (2011-2016)

Table TSMC Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table TSMC Fan-in Wafer Level Packaging Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure TSMC Fan-in Wafer Level Packaging Market Share (2011-2016)

Table Texas Instruments Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table Texas Instruments Fan-in Wafer Level Packaging Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure Texas Instruments Fan-in Wafer Level Packaging Market Share (2011-2016)

Table Rudolph Technologies Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table Rudolph Technologies Fan-in Wafer Level Packaging Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure Rudolph Technologies Fan-in Wafer Level Packaging Market Share (2011-2016)

Table SEMES Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table SEMES Fan-in Wafer Level Packaging Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure SEMES Fan-in Wafer Level Packaging Market Share (2011-2016)

Table SUSS MicroTec Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table SUSS MicroTec Fan-in Wafer Level Packaging Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure SUSS MicroTec Fan-in Wafer Level Packaging Market Share (2011-2016)

Table Ultratech Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table Ultratech Fan-in Wafer Level Packaging Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure Ultratech Fan-in Wafer Level Packaging Market Share (2011-2016)

Table FlipChip International Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table FlipChip International Fan-in Wafer Level Packaging Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure FlipChip International Fan-in Wafer Level Packaging Market Share (2011-2016)

Table IWLPC Basic Information, Manufacturing Base, Sales Area and Its Competitors

Table IWLPC Fan-in Wafer Level Packaging Capacity, Production, Revenue, Price and Gross Margin (2011-2016)

Figure IWLPC Fan-in Wafer Level Packaging Market Share (2011-2016)

Figure China Fan-in Wafer Level Packaging Capacity, Production and Growth (2011-2016)

Figure China Fan-in Wafer Level Packaging Revenue (Million USD) and Growth (2011-2016)

Table China Fan-in Wafer Level Packaging Production, Consumption, Export and Import (2011-2016)

Table China Fan-in Wafer Level Packaging Production by Type (2011-2016)

Table China Fan-in Wafer Level Packaging Production Share by Type (2011-2016)

Figure Production Market Share of Fan-in Wafer Level Packaging by Type (2011-2016)

Figure 2015 Production Market Share of Fan-in Wafer Level Packaging by Type

Table China Fan-in Wafer Level Packaging Revenue by Type (2011-2016)

Table China Fan-in Wafer Level Packaging Revenue Share by Type (2011-2016)

Figure Production Revenue Share of Fan-in Wafer Level Packaging by Type (2011-2016)

Figure 2015 Revenue Market Share of Fan-in Wafer Level Packaging by Type

Table China Fan-in Wafer Level Packaging Price by Type (2011-2016)

Figure China Fan-in Wafer Level Packaging Production Growth by Type (2011-2016)

Table China Fan-in Wafer Level Packaging Consumption by Application (2011-2016)

Table China Fan-in Wafer Level Packaging Consumption Market Share by Application (2011-2016)

Figure China Fan-in Wafer Level Packaging Consumption Market Share by Application in 2015

Table China Fan-in Wafer Level Packaging Consumption Growth Rate by Application

(2011-2016)

Figure China Fan-in Wafer Level Packaging Consumption Growth Rate by Application

(2011-2016)

Table China Fan-in Wafer Level Packaging Production by Regions

(Provinces)(2011-2016)

Table China Fan-in Wafer Level Packaging Production Market Share by Regions

(Provinces)(2011-2016)

Table China Fan-in Wafer Level Packaging Production Value by Regions

(Provinces)(2011-2016)

Table China Fan-in Wafer Level Packaging Production Value Market Share by Regions

(Provinces)(2011-2016)

Table China Fan-in Wafer Level Packaging Sales Price by Regions

(Provinces)(2011-2016)

Table China Fan-in Wafer Level Packaging Consumption by Regions

(Provinces)(2011-2016)

Table China Fan-in Wafer Level Packaging Consumption Market Share by Regions

(Provinces)(2011-2016)

Table China Fan-in Wafer Level Packaging Production, Consumption, Export and Import (2011-2016)

Table Production Base and Market Concentration Rate of Raw Material

Figure Price Trend of Key Raw Materials

Table Key Suppliers of Raw Materials

Figure Manufacturing Cost Structure of Fan-in Wafer Level Packaging

Figure Manufacturing Process Analysis of Fan-in Wafer Level Packaging

Figure Fan-in Wafer Level Packaging Industrial Chain Analysis

Table Raw Materials Sources of Fan-in Wafer Level Packaging Major Manufacturers in 2015

Table Major Buyers of Fan-in Wafer Level Packaging

Table Distributors/Traders List

Figure China Fan-in Wafer Level Packaging Capacity, Production and Growth Rate

Forecast (2016-2021)

Figure China Fan-in Wafer Level Packaging Revenue and Growth Rate Forecast

(2016-2021)

Table China Fan-in Wafer Level Packaging Production, Import, Export and Consumption Forecast (2016-2021)

Table China Fan-in Wafer Level Packaging Production Forecast by Type (2016-2021)

Table China Fan-in Wafer Level Packaging Consumption Forecast by Application (2016-2021)

Table China Fan-in Wafer Level Packaging Production Forecast by Regions

(Provinces)(2016-2021)

Table China Fan-in Wafer Level Packaging Consumption Forecast by Regions

(Provinces)(2016-2021)

Table China Fan-in Wafer Level Packaging Production, Consumption, Import and Export Forecast by Regions (Provinces)(2016-2021)

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